

20N60-VB Datasheet N-Channel 650 V (D-S) MOSFET

PRODUCT SUMMARY						
V _{DS} (V) at T _J max.	650					
R _{DS(on)} (Ω) at 25 °C	$V_{GS} = 10 V$	0.36				
Q _g max. (nC)	106					
Q _{gs} (nC)	14					
Q _{gd} (nC)	33					
Configuration	Single					

FEATURES

- Reduced t_{rr} , Q_{rr} , and I_{RRM}
- Low figure-of-merit (FOM) Ron x Qa
- Low input capacitance (C_{iss})
- Low switching losses due to reduced Q_{rr}
- Ultra low gate charge (Q_q)
- Avalanche energy rated (UIS)

APPLICATIONS

- Telecommunications
- Server and telecom power supplies Lighting
 - High-intensity discharge (HID)
 - Fluorescent ballast lighting
- Consumer and computing
- ATX power supplies
- Industrial
 - Welding
 - Battery chargers
- Renewable energy
 - Solar (PV inverters)
- Switch mode power supplies (SMPS)

ABSOLUTE MAXIMUM RATINGS ($T_C = 25 \text{ °C}$, unless otherwise noted)									
PARAMETER			SYMBOL	LIMIT	UNIT				
Drain-Source Voltage			V _{DS}	650	V				
Gate-Source Voltage			V _{GS}	± 30					
Continuous Drain Current (T _J = 150 °C)	V _{GS} at 10 V	T _C = 25 °C T _C = 100 °C	- I _D	18					
	V _{GS} at 10 V	T _C = 100 °C		16	A				
Pulsed Drain Current ^a			I _{DM}	53					
Linear Derating Factor				1.7	W/°C				
Single Pulse Avalanche Energy ^b			E _{AS}	367	mJ				
Maximum Power Dissipation			PD	208	W				
Operating Junction and Storage Temperature Range			T _J , T _{stg}	-55 to +150	°C				
Drain-Source Voltage Slope	T _J = 125 °C			37	V/ns				
Reverse Diode dV/dt ^d		dV/dt	31	v/ns					
Soldering Recommendations (Peak Temperature) ^c	for 10 s			300	°C				

S

N-Channel MOSFET

Notes

a. Repetitive rating; pulse width limited by maximum junction temperature. b. $V_{DD} = 50$ V, starting T_J = 25 °C, L = 28.2 mH, R_g = 25 Ω , I_{AS} = 5.1 A.

c. 1.6 mm from case.

d. $I_{SD} \leq I_D$, dl/dt = 100 A/µs, starting T_J = 25 °C.

TO-247AC

G

Top View





THERMAL RESISTANCE RAT	NGS							
PARAMETER	SYMBOL	TYP.		MAX.		UNIT		
Maximum Junction-to-Ambient	R _{thJA}	- 62						
Maximum Junction-to-Case (Drain)	R _{thJC}	- 0.5				°C/W		
SPECIFICATIONS (T _J = 25 °C, u	unless otherwi	se noted)						
PARAMETER	SYMBOL	TES	T CONDIT	IONS	MIN.	TYP.	MAX.	UNIT
Static	I				<u> </u>	1	I	
Drain-Source Breakdown Voltage	V _{DS}	V _{GS} :	= 0 V, I _D =	250 µA	650	-	-	V
V _{DS} Temperature Coefficient	$\Delta V_{DS}/T_{J}$	Referenc	e to 25 °C,	$I_D = 1 \text{ mA}$	-	0.67	-	V/°C
Gate-Source Threshold Voltage (N)	V _{GS(th)}	V _{DS} =	= V _{GS} , I _D =	250 µA	2	-	4	V
Cata Sauraa Laakaga		$V_{GS} = \pm 20 V$ $V_{GS} = \pm 30 V$		-	-	± 100	nA	
Gate-Source Leakage	I _{GSS}			-	-	± 1	μA	
Zaro Gata Voltago Drain Current		V _{DS} =	V _{DS} = 520 V, V _{GS} = 0 V			-	1	
Zero Gate Voltage Drain Current	IDSS	V _{DS} = 520 \	/, V _{GS} = 0 '	-	-	500	μA	
Drain-Source On-State Resistance	R _{DS(on)}	$V_{GS} = 10 V$	I	_D = 11 A	-	0.36	-	Ω
Forward Transconductance	9 _{fs}	V _{DS}	= 30 V, I_D	= 11 A	-	7.0	-	S
Dynamic							•	-
Input Capacitance	C _{iss}		V _{GS} = 0 \	′.	-	2322	-	
Output Capacitance	C _{oss}	$V_{DS} = 100 \text{ V},$ f = 1 MHz		-	105	-	pF	
Reverse Transfer Capacitance	C _{rss}			-	4	-		
Effective Output Capacitance, Energy Related ^a	C _{o(er)}	V_{DS} = 0 V to 520 V, V_{GS} = 0 V		-	84	-		
Effective Output Capacitance, Time Related ^b	C _{o(tr)}			-	293	-		
Total Gate Charge	Qg				-	71	106	
Gate-Source Charge	Q _{gs}	$V_{GS} = 10 \text{ V}$ $I_D = 11 \text{ A}, V_{DS} = 520 \text{ V}$		-	14	-	nC	
Gate-Drain Charge	Q _{gd}				-	33	-	1
Turn-On Delay Time	t _{d(on)}		V_{DD} = 520 V, I_D = 11 A, V_{GS} = 10 V, R_g = 9.1 Ω		-	22	44	ns
Rise Time	t _r	V _{DD} =			-	34	68	
Turn-Off Delay Time	t _{d(off)}	V _{GS} =			-	68	102	
Fall Time	t _f			-	42	84		
Gate Input Resistance	R _g	f = 1 MHz, open drain		-	0.78	-	Ω	
Drain-Source Body Diode Characteristi	cs							
Continuous Source-Drain Diode Current	١ _S	MOSFET symbol showing the integral reverse p - n junction diode		-	-	21	A	
Pulsed Diode Forward Current	I _{SM}			-	-	53		
Diode Forward Voltage	V _{SD}	T _J = 25 °C	T _J = 25 °C, I _S = 11 A, V _{GS} = 0 V		-	0.9	1.2	V
Reverse Recovery Time	t _{rr}				-	160	-	ns
Reverse Recovery Charge	Q _{rr}	$T_J = 25 \ ^{\circ}C, I_F = I_S = 11 \ A,$ dl/dt = 100 A/µs, V _R = 25 V		-	1.2	-	μC	
Reverse Recovery Current	I _{RRM}			-	14	-	A	

Notes

a. $C_{oss(er)}$ is a fixed capacitance that gives the same energy as C_{oss} while V_{DS} is rising from 0 % to 80 % V_{DSS} . b. $C_{oss(tr)}$ is a fixed capacitance that gives the same charging time as C_{oss} while V_{DS} is rising from 0 % to 80 % V_{DSS} .



TYPICAL CHARACTERISTICS (25 °C, unless otherwise noted)

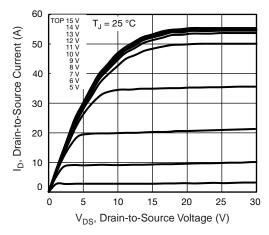


Fig. 1 - Typical Output Characteristics



Fig. 2 - Typical Output Characteristics

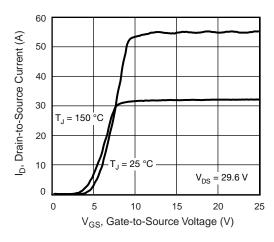


Fig. 3 - Typical Transfer Characteristics

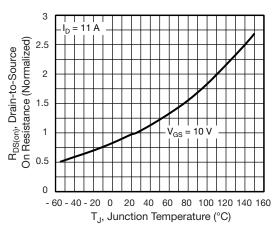


Fig. 4 - Normalized On-Resistance vs. Temperature

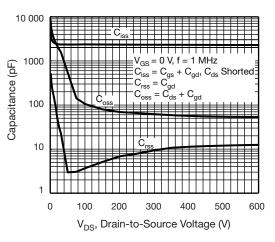


Fig. 5 - Typical Capacitance vs. Drain-to-Source Voltage



Fig. 6 - C_{oss} and E_{oss} vs. V_{DS}



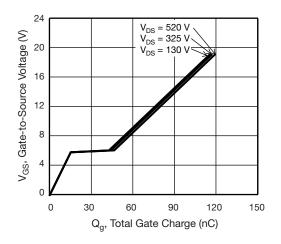


Fig. 7 - Typical Gate Charge vs. Gate-to-Source Voltage

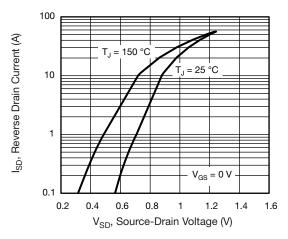


Fig. 8 - Typical Source-Drain Diode Forward Voltage

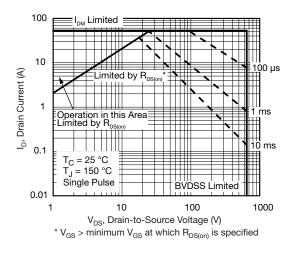


Fig. 9 - Maximum Safe Operating Area

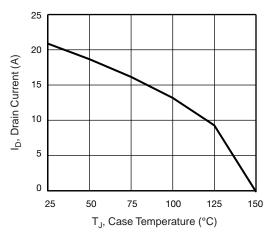


Fig. 10 - Maximum Drain Current vs. Case Temperature



Fig. 11 - Temperature vs. Drain-to-Source Voltage



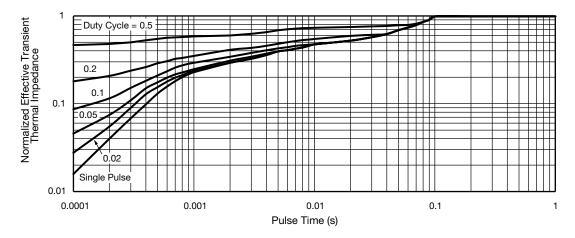


Fig. 12 - Normalized Thermal Transient Impedance, Junction-to-Case



Fig. 13 - Switching Time Test Circuit

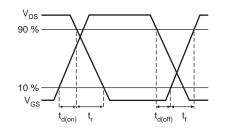


Fig. 14 - Switching Time Waveforms



Fig. 15 - Unclamped Inductive Test Circuit

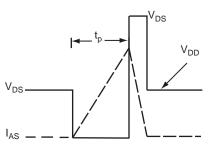


Fig. 16 - Unclamped Inductive Waveforms

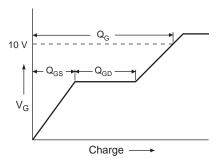


Fig. 17 - Basic Gate Charge Waveform

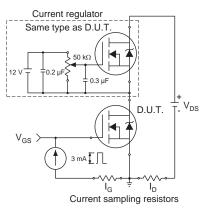
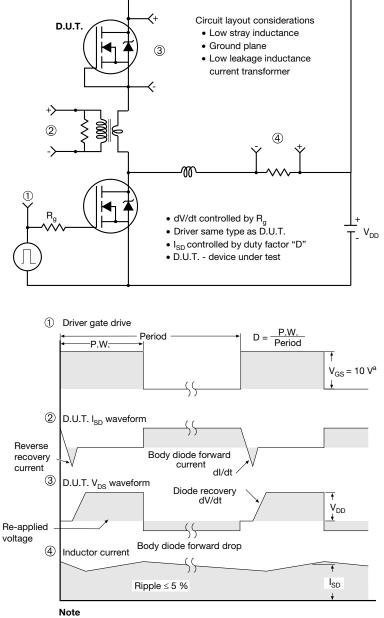


Fig. 18 - Gate Charge Test Circuit



Peak Diode Recovery dV/dt Test Circuit



a. $V_{GS} = 5$ V for logic level devices

Fig. 19 - For N-Channel



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